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Thermosense: Thermal Infrared Applications XLIV

Arantza Mendioroz
Nicolas P. Avdelidis
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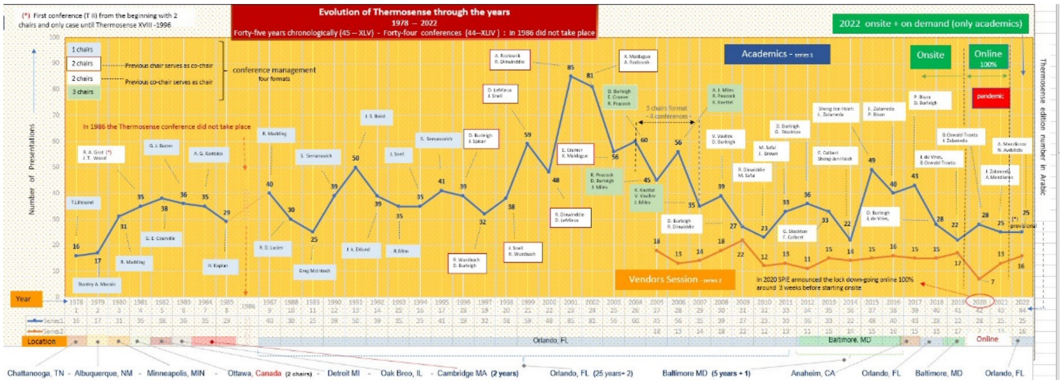
Introduction

The Thermosense: Thermal Infrared Applications XLIV conference, part of SPIE Defense + Commercial Sensing, was held 3-7 April 2022 in Orlando, Florida. In addition to the in-person conference, an on-demand forum was offered to facilitate participation. The conference started with the XVIII edition of the Vendor Presentation and Reception Session, organized by A. E. Rozlosnik (SI Termografía Infrarroja, Argentina) and S.-J. Hsieh (Texas A&M University, USA), which comprised 16 presentations by SPIE DCS 2022 exhibitors exposing the latest advances in commercial infrared cameras, detectors, systems and equipment.

The technical program covered the latest thermal infrared applications, developments and techniques, organized in the following sessions: Additive Manufacturing, Novel Techniques, Thermophysical Properties, Hyperspectral and Multi-Imaging Applications, IR NDT at the Microscale, IR NDT of Composites and Multilayered Structures, AI in Thermal Imaging Applications, IR NDT in Industry and Infrastructures, Biomedical Applications and Thermal Modelling and Signal Processing.

This volume contains technical papers presented at the Thermosense: Thermal Infrared Applications XLIV technical sessions, both in-person and at the on-demand forum.



Arantza Mendioroz
Nicolas P. Avdelidis